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PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
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HITOSHI CHIBA	09/29/2014

RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14391897

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DATE SIGNED:	10/10/2014

503014801 PATENT REEL: 033931 FRAME: 0274

Total Attachments: 2 source=Assignment#page1.tif source=Assignment#page2.tif

PATENT REEL: 033931 FRAME: 0275

Assignment of Application

I (We),
Yasuki ITOH of c/o Kagamida Factory, Denka Seiken Co., Ltd., 1359-1, Aza Kagamida,
Kigoshi, Gosen-shi, Niigata 959-1695 Japan and
Hitoshi CHIBA of c/o NATIONAL UNIVERSITY CORPORATION HOKKAIDO
UNIVERSITY, Kita 8-jyo Nishi 5-chome, Kita-ku, Sapporo-shi, Hokkaido 060-0808
<u>Japan</u> , respectively,
have invented certain new and useful improvements in:
METHOD FOR QUANTIFYING SUBFRACTION OF CHOLESTEROL (-C) IN
HIGH-DENSITY LIPOPROTEIN (HDL)
for which an application for Letters Patent was executed on
(Application No. <u>PCT/JP2013/060778</u> , filed <u>April 10, 2013</u>), and
WHEREAS,
DENKA SEIKEN CO., LTD. and
NATIONAL UNIVERSITY CORPORATION HOKKAIDO UNIVERSITY
(hereinafter referred to as "ASSIGNEES") having a places of business at:
1-1, Nihonbashi Muromachi 2-chome, Chuo-ku, Tokyo 103-8338 Japan and
Kita 8-iyo Nishi 5-chome, Kita-ku, Sapporo-shi, Hokkaido 060-0808 Japan
are desirous of acquiring the entire right, title and interest in and to said invention and in and to
any Letters Patent that may be granted therefore in the United States and its territorial possessions
and in any and all foreign countries;

NOW, THEREFORE, in consideration of the sum of FIVE DOLLARS (\$5.00), the receipt whereof is hereby acknowledged, and for other good and valuable consideration, I (WE), by these presents do sell, assign and transfer unto said ASSIGNEES, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters Patent which may be granted therefore in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations, substitutions and renewals thereof.

I (WE) hereby authorize and request the Patent Office Officials in the United States and its territorial possessions and any official of any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEES as the assignee of my (our) entire right, title and interest in and to the same, for the sole use and behoof of said ASSIGNEES, its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me (us) had this Assignment and sale not been made.

PATENT REEL: 033931 FRAME: 0276 Further, I (WE) agree that I (WE) will communicate to said ASSIGNEES or their legal representatives and assigns covenant and any facts known to me (us) respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letter Patent to be issued to said ASSIGNEES, make all rightful oaths, and, generally do everything possible to aid said ASSIGNEES, its (his) successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.

The undersigned hereby grant(s) the firm of Foley & Lardner of Washington Harbour, 3000 K. Street, N.W., Suite 600, Washington, D.C. 20007-5109 U.S.A. the power to insert on this assignment any further identification, including the application number and filing date, which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date: Sep. 22. 2014 (Signature of inventor) Yasuki ITOH

Date: Sep. 29, 2014 Witoshi Chiha

(Signature of inventor) Hitoshi CHIBA

PATENT REEL: 033931 FRAME: 0277

RECORDED: 10/10/2014